



News Release

SC-RFID

Media Contacts:

Cindy Huff	Texas Instruments	214-567-2463	chuff@ti.com
Ashley Peterson	Bridgeman Communications	617-742-7270	ashley@bridgeman.com

(Please do not publish these numbers or email addresses.)

Texas Instruments' Ultra-Thin Chip Module Enables Production of High-Quality Graphics-Rich Branded Contactless Cards

Thinnest module available allows use of more durable print stock and improves production yield

DALLAS (May 5, 2008) – Taking its cue from customers and a page out of the fashion magazines where “thin is always in,” Texas Instruments Incorporated (TI) (NYSE: TXN) today announced the availability of its ultra-thin module for contactless payment applications which removes another technology barrier for broader proliferation of contactless payment. Now 26 percent thinner than conventional packaged contactless chip offerings, the new ultra-thin module enables card manufacturers to produce an increasing array of colorful and distinctive products with higher yields as a result of causing fewer visual imperfections than thicker chip modules. (See www.ti.com/ultra-thin)

Banks are increasingly offering new graphics-rich contactless cards to differentiate their brand and stay “top of wallet” with consumers. Over the next few years, banks will issue more than 50 million opaque contactless cards annually with the expectation that number will double in 2010 (ABI Research). Using the new TI ultra-thin module, the industry’s thinnest contactless payment chip, card manufacturers can create thinner PVC pre-laminate sheets for the contactless layer. The 280um (11mil) ultra-thin module enables the creation of pre-laminates as thin as 345um (13.6 mil). This allows the card manufacturers to print the card’s colorful artwork on thicker print stock while maintaining the 680-840um (26.8-33.1 mil) ISO standard for card thickness. Thicker print stock makes these complex cards more durable and able to survive multiple passes through a printing press during standard card manufacturing processes, translating to higher yields of finished cards.

- More -

“With the new ultra-thin design of our contactless payment module, card manufacturers can achieve higher production yields, while keeping bank customer satisfaction high and giving them the flexibility to bring to market a new range of exciting new card products” said Trevor Pavey, manager of contactless payment at Texas Instruments.

“The new ultra thin module developed by Texas Instruments will allow printing on much thicker core stocks. This development supports the use of more complicated artwork on contactless cards, thus enabling intricate designs rivaling the best art seen on conventional cards today,” said Jean Francois Durand, Vice President of Global Manufacturing Operations for Oberthur Technologies of America Corp. “These powerful designs are extremely important to promoting card and brand recognition in the banking card industry.”

TI’s ultra-thin module operates at extremely low power, delivers a fast transaction speed (typically 120 milliseconds) and is developed with a highly sensitive radio frequency chip (see www.ti.com/waveandgo) to enable a successful transaction the first time a customer taps the card to the payment reader. The module and payment application software operate in dynamic Card Verification Code (CVC) transaction authorization mode which offers issuers the highest level of security available.

“The use of the TI ultra-thin contactless payment module integrates TI’s radio frequency performance into a thin new design that enables our banking customers to create unique contactless cards with high-quality, bold new graphics that keep their products ‘top of wallet’ with consumers,” said Matt Smoczynski, VP of Marketing of Perfect Plastic Printing. “We are really excited about the flexibility this ultra-thin packaging brings to our contactless product offering.”

- More -



The ultra-thin module packaging will be available in MasterCard PayPass™ and other contactless payment products. For more information on TI's ultra-thin module and its contactless payment technology and applications, TI will be available to meet at CTST 2008, May 12-15 in Orlando, Florida or visit <http://www.ti.com/contactless>.

#

About Texas Instruments

A technology pioneer in secured contactless applications, Texas Instruments delivers many innovative contactless and secure products to the forefront of electronic ID and payments market. ExxonMobil's SpeedPass™ and card issuers such as MasterCard leveraged TI's technical expertise in providing the first "pay-at-the-pump" application and the innovative contactless credit card design and form factors. TI is developing faster, more secure smart IC applications for the next generation of contactless electronic government-issued identification. High-performance and low-power contactless applications continue to be evidence of TI's strength in designing robust, yet streamlined products that execute more efficiently. Capitalizing on its competencies in high-volume semiconductor manufacturing and microelectronics packaging, TI is a visionary leader and at the forefront of establishing new markets and international standards for secured contactless applications. For more information, call 1-800-962-7343, or visit the www.ti.com/contactless.

Texas Instruments (NYSE: TXN) helps customers solve problems and develop new electronics that make the world smarter, healthier, safer, greener and more fun. A global semiconductor company, TI innovates through manufacturing, design and sales operations in more than 25 countries. For more information, go to www.ti.com, or visit TI's RFID web site at www.ti.com/rfid.